Part Number: XLMDK11D5V

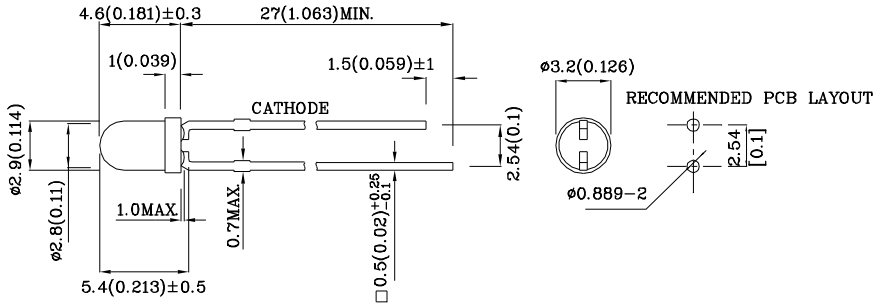
T-1 (3mm) SOLID STATE LAMP

Features

- Radial / Through hole package
- Reliable & robust
- Low power consumption
- Available on tape and reel
- 5V internal resistor.
- RoHS Compliant

ATTENTION
OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Package Schematics



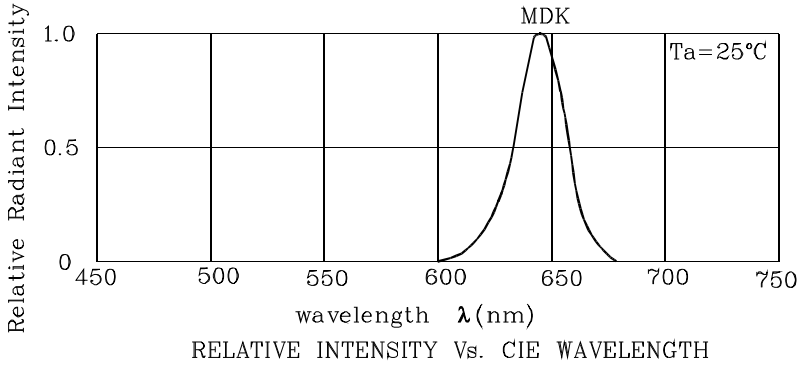
Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A=25°C)		**MDK (AlGaInP)**	**Unit**
Reverse Voltage	V_R	5	V
Forward Voltage	V_F	6	V
Power Dissipation	P_D	85	mW
Operating Temperature	T_A	-40 ~ +70	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

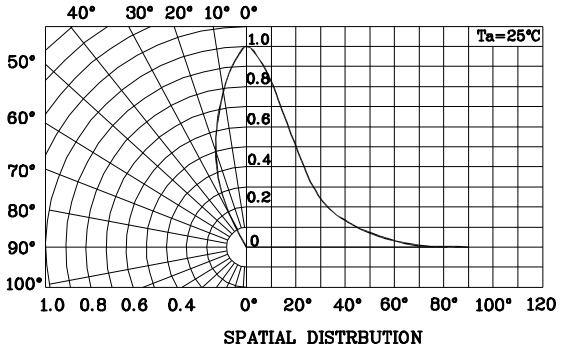
Operating Characteristics (T_A=25°C)		**MDK (AlGaInP)**	**Unit**
Forward Current (Typ.) (V_F=5V)	I_F	13	mA
Forward Current (Max.) (V_F=5V)	I_F	17.5	mA
Reverse Current (Max.) (V_R=5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (V_F=5V)	λP	645*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (V_F=5V)	λD	630*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (V_F=5V)	△λ	28	nm

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (V_F=5V) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 2θ 1/2
				min.	typ.		
XLMDK11D5V	Red	AlGaInP	Red Diffused	200 50*	397 98*	645*	40°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

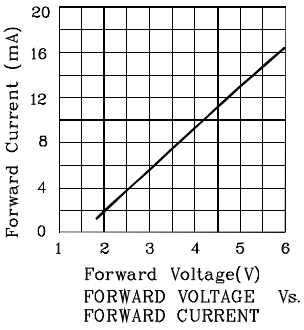


RELATIVE INTENSITY Vs. CIE WAVELENGTH

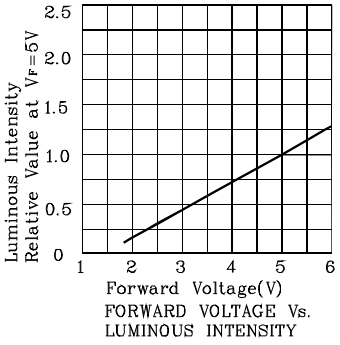


SPATIAL DISTRBUTION

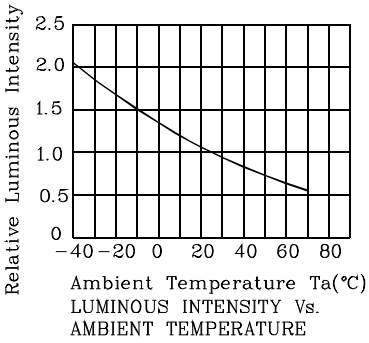
❖ MDK



FORWARD VOLTAGE Vs.
FORWARD CURRENT

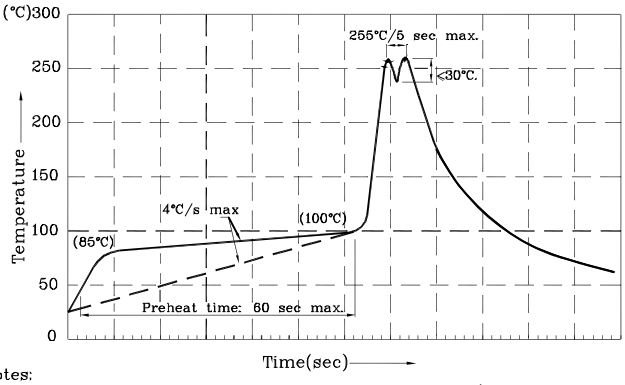


FORWARD VOLTAGE Vs.
LUMINOUS INTENSITY



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)

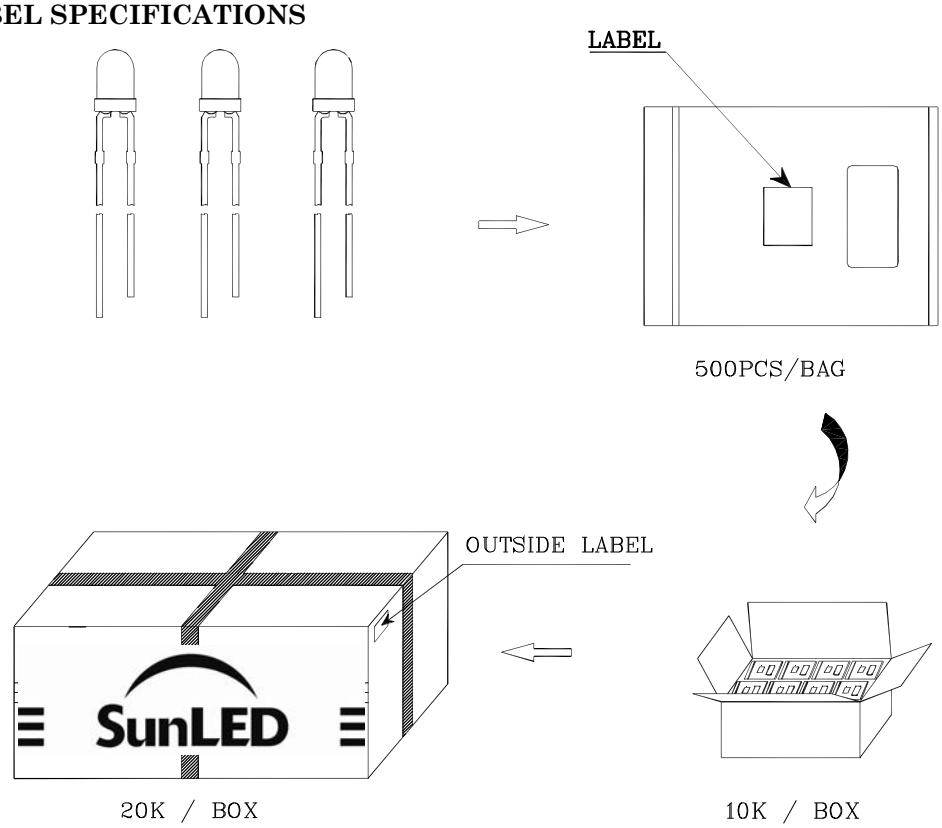


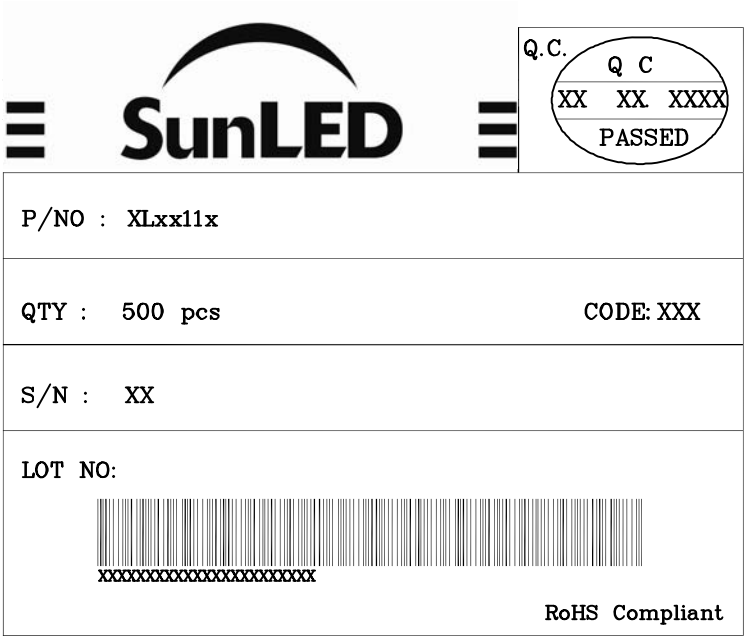
Notes:
1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on Luminous intensity/ luminous flux, or wavelength),
the typical accuracy of the sorting process is as follows:
1. Wavelength: +/-1nm
2. Luminous intensity/ luminous flux: +/-15%
Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS





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2. Contents within this document are subject to improvement and enhancement changes without notice.
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